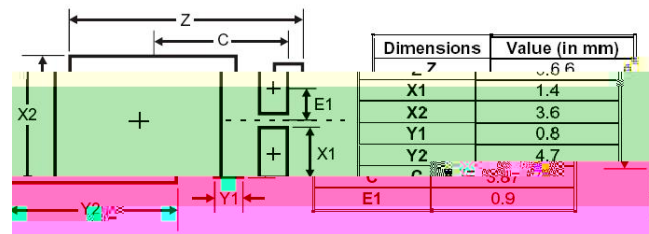
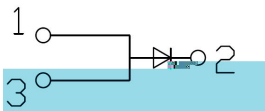


Schottky Barrier Diode in a TO-277 Plastic Package.

Low forward voltage drop, low power losses, High efficiency operation. HF Product.

For use in high frequency inverters, switching power supplies, freewheeling diodes, OR-ing diode, dc-to-dc converters and reverse battery protection.



PIN1 Anode PIN 2 Cathode PIN 3 Anode

Suggested Pad layout

See Marking Instructions.

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RM} V_{RSM} V_{DC}	50	V
RMS Voltage	V_{RMS}	35	V
Average Rectified Forward Current	$I_{F(AV)}$	1×15	A
Non Repetitive Peak Surge Current	I_{FSM}	280	A
Thermal Resistance Junction to Case Note 1	R_{JC}	73	/W
Junction and Storage Temperature Range	T_j T_{stg}	-40 +150	

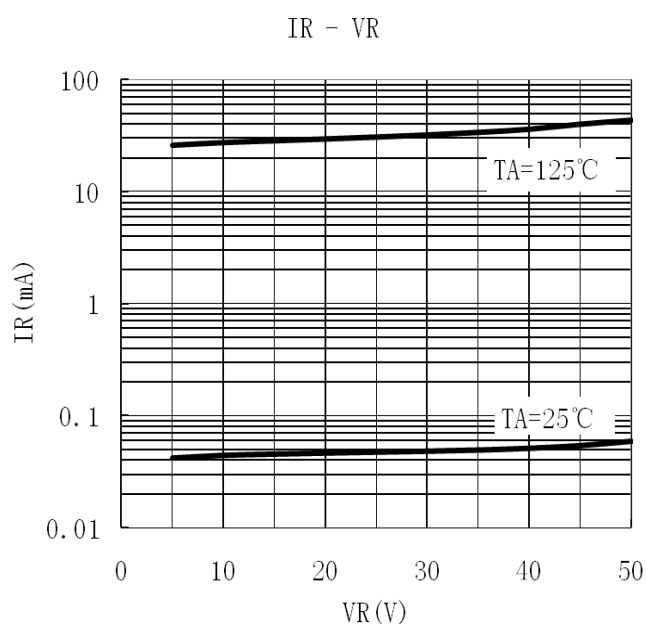
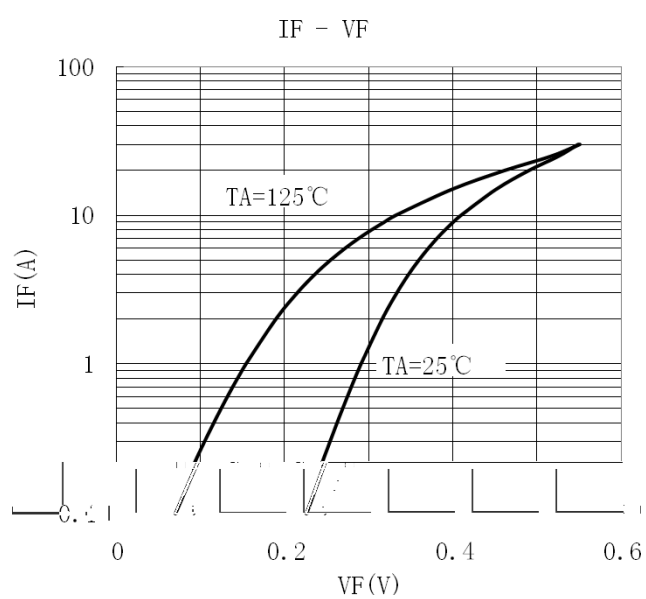
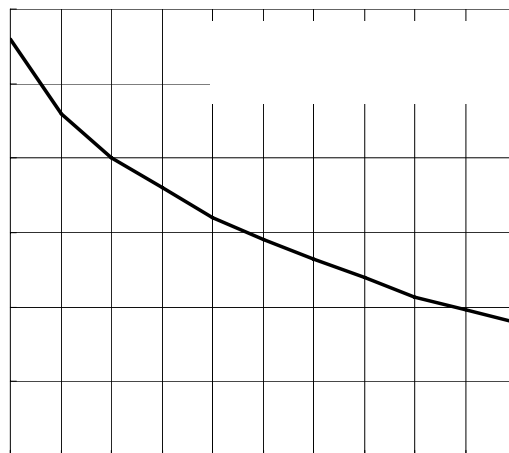
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Breakdown Voltage	V_{BR}	$I_R=1mA(T_a=25^\circ C)$	50			V
Forward Voltage	V_F	$I_F=3A(T_a=25^\circ C)$		0.33	0.42	V
		$I_F=3A(T_a=125^\circ C)$		0.22	0.28	V
		$I_F=15A(T_a=25^\circ C)$		0.45	0.47	V
		$I_F=15A(T_a=125^\circ C)$		0.40	0.45	V
Instantaneous Reverse Current	I_R Note 2	$V_R=50V(T_a=25^\circ C)$		80	150	A
		$V_R=50V(T_a=100^\circ C)$			30	mA
		$V_R=50V(T_a=125^\circ C)$			50	mA

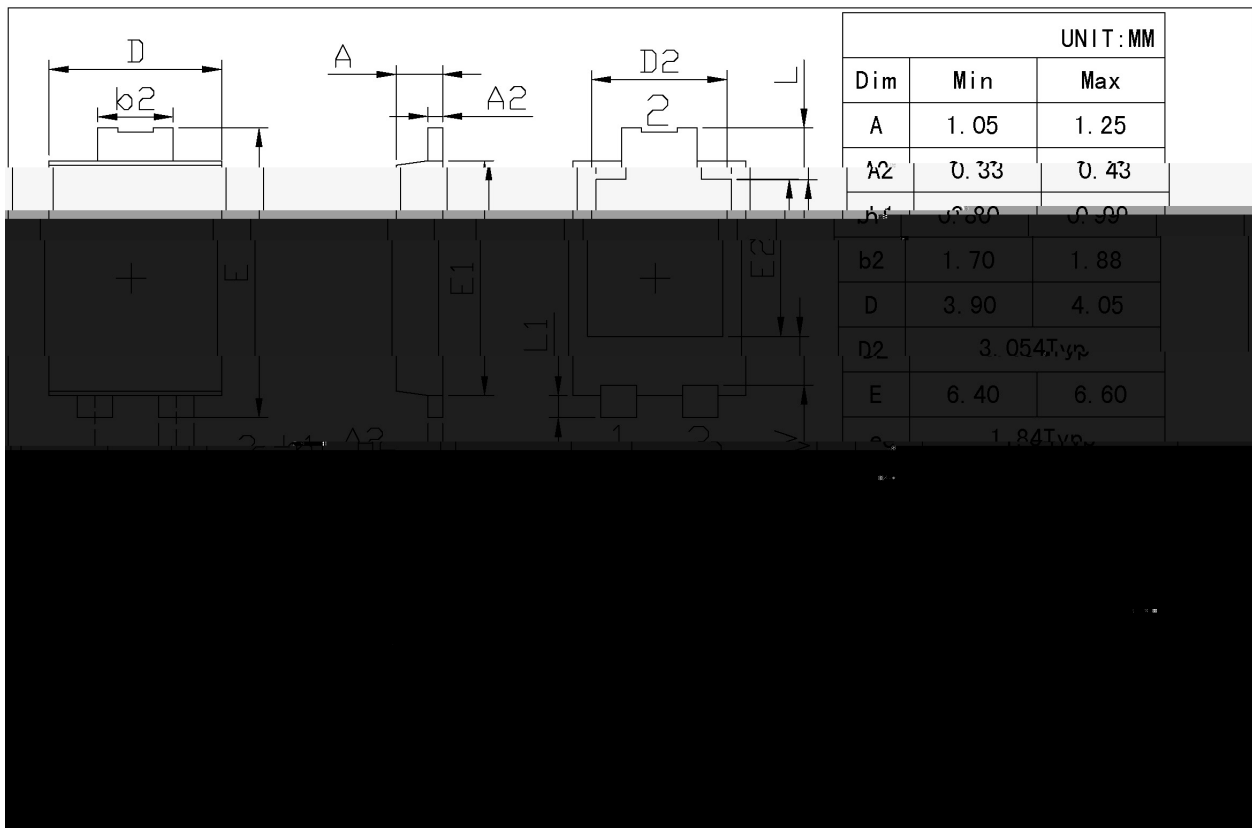
Notes

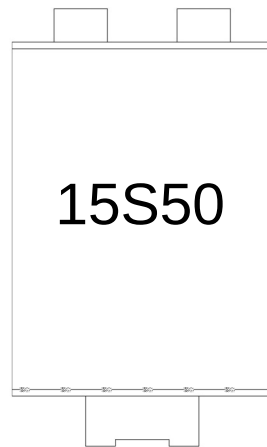
FR-4 PCB, 2oz. Copper, minimum recommended pad layout per.

Short duration pulse test used to minimize self-heating effect.

Unless otherwise noted, values for the parameters of a single chip







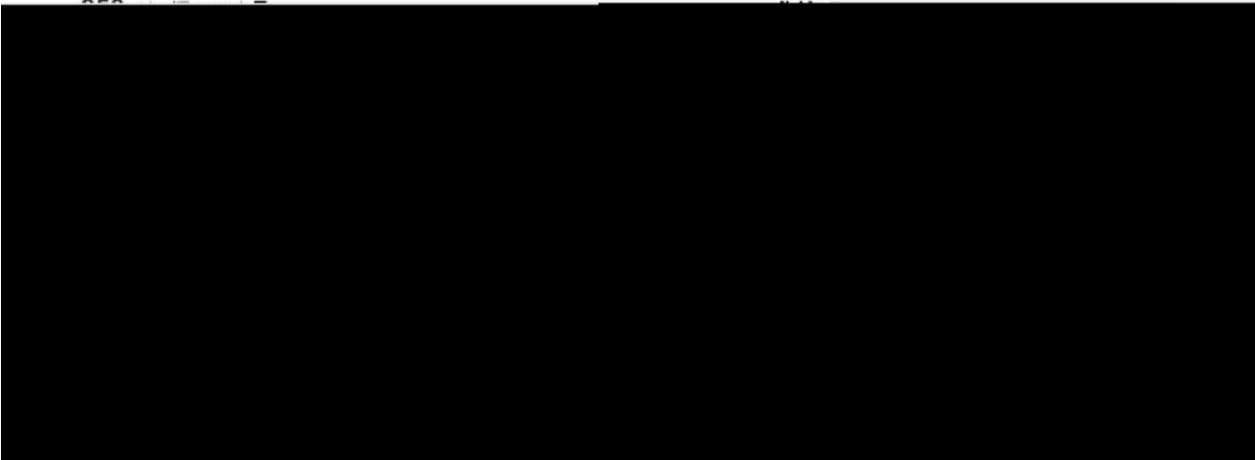
Note:

Product Type.

****:

Lot No. Code, code change with Lot No.

Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

150 180

60 90sec;

1.Preheating:150~180 , Time:60~90sec.
- 2

245 5

5 0.5sec;

2.Peak Temp.:245 5 , Duration:5 0.5sec.
- 3

2 10

/sec.

3. Cooling Speed: 2~10 /sec.

260 5

10 1 sec.

Temp.:260±5

Time:10±1 sec

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱